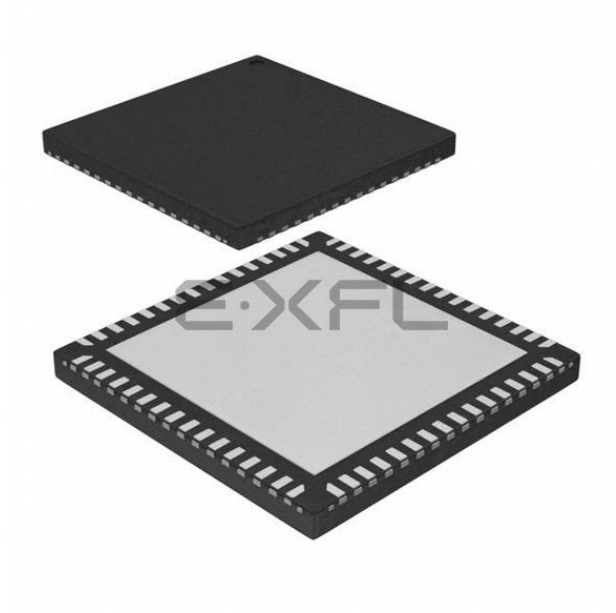

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	47
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3n0ba-mur

1. SAM3N Description

Atmel's SAM3N series is a member of a family of Flash microcontrollers based on the high performance 32-bit ARM Cortex-M3 RISC processor. It operates at a maximum speed of 48 MHz and features up to 256 Kbytes of Flash and up to 24 Kbytes of SRAM. The peripheral set includes 2x USARTs, 2x UARTs, 2x TWIs, 3x SPI, as well as 1 PWM timer, 6x general purpose 16-bit timers, an RTC, a 10-bit ADC and a 10-bit DAC.

The SAM3N series is ready for capacitive touch thanks to the QTouch library, offering an easy way to implement buttons, wheels and sliders.

The SAM3N device is an entry-level general purpose microcontroller. That makes the SAM3N the ideal starting point to move from 8- /16-bit to 32-bit microcontrollers.

It operates from 1.62V to 3.6V and is available in 48-pin, 64-pin and 100-pin QFP, 48-pin and 64-pin QFN, and 100-pin BGA packages.

The SAM3N series is the ideal migration path from the SAM3S for applications that require a reduced BOM cost. The SAM3N series is pin-to-pin compatible with the SAM3S series. Its aggressive price point and high level of integration pushes its scope of use far into cost-sensitive, high-volume applications.

Figure 2-2. SAM3N 64-pin version Block Diagram

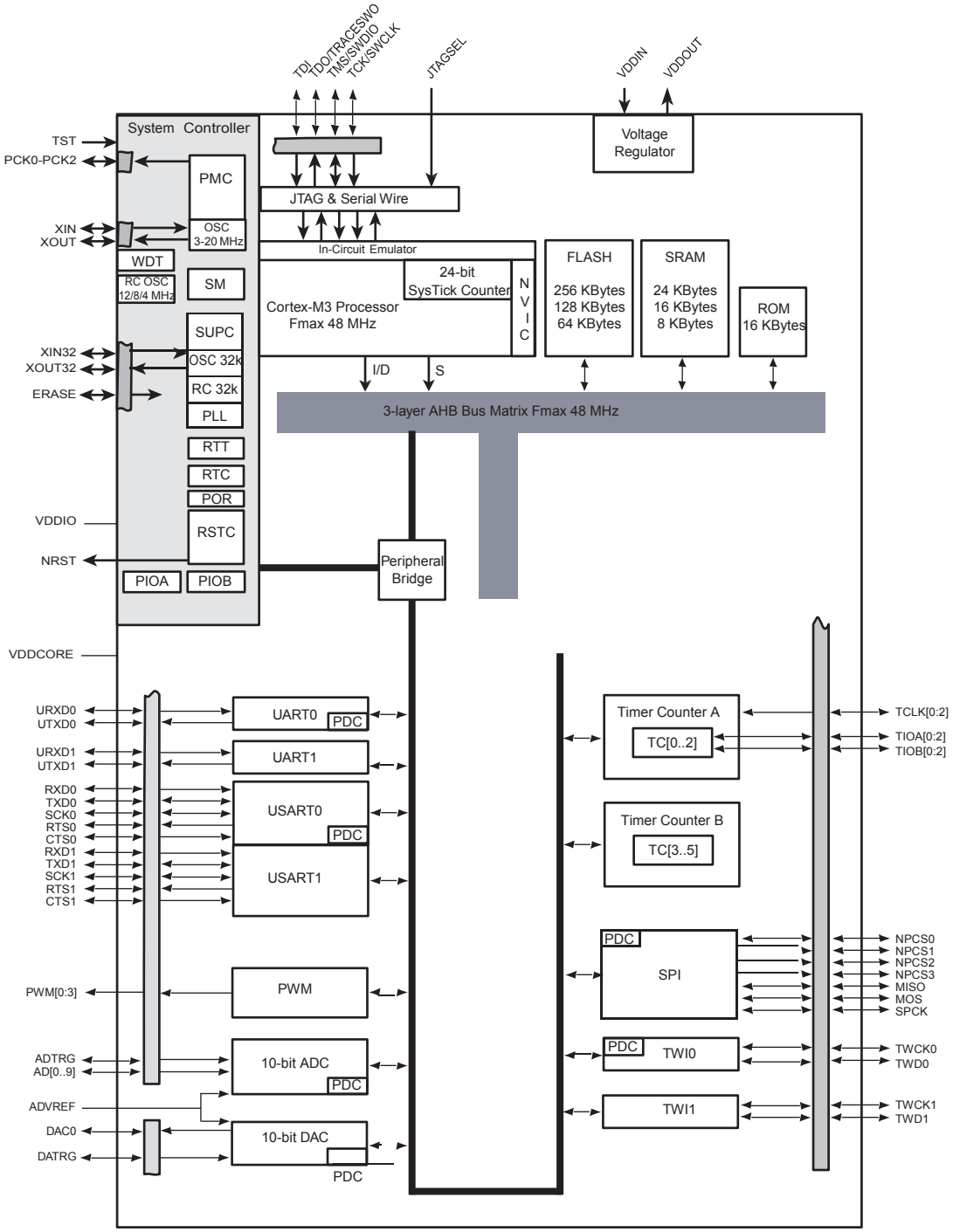
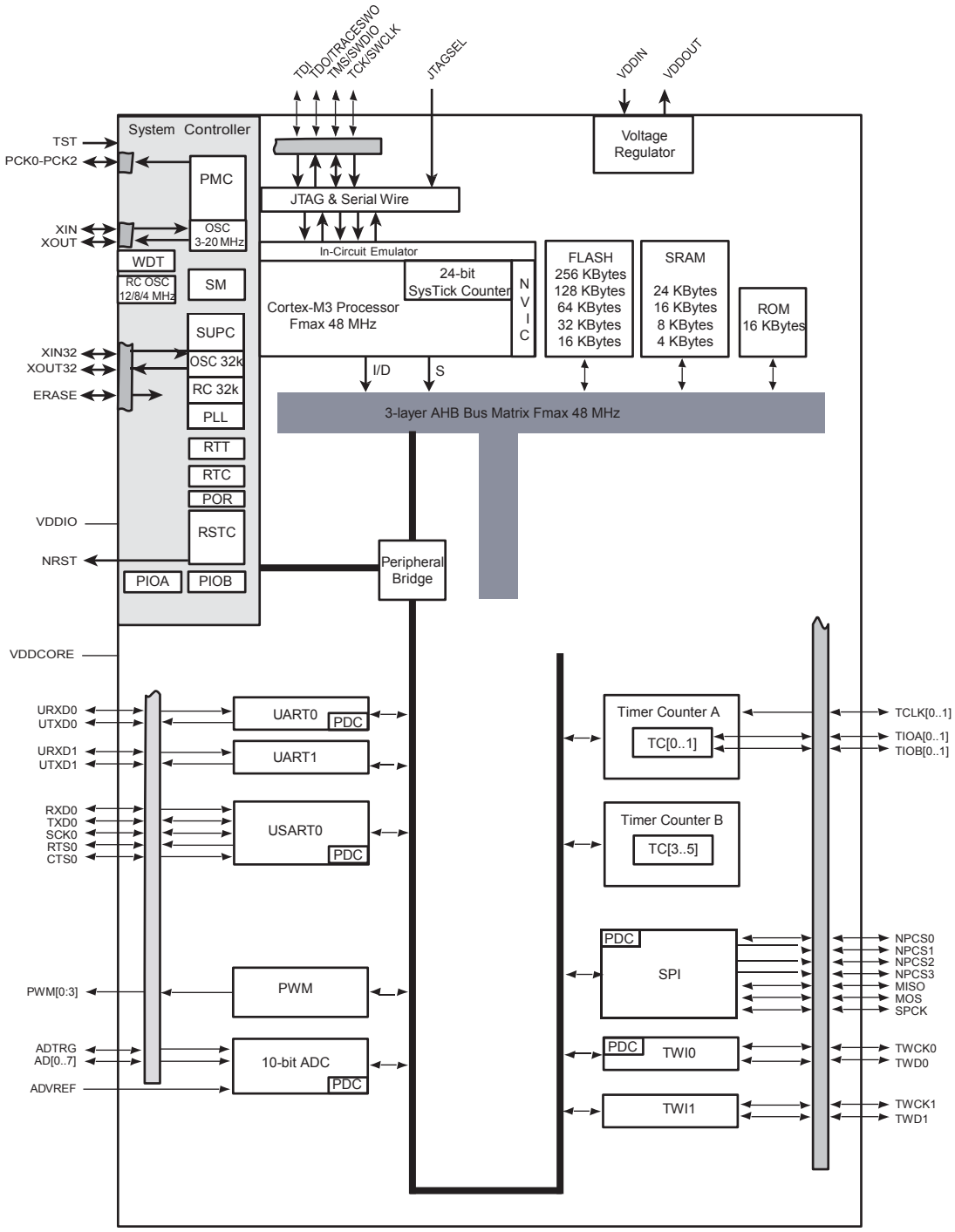


Figure 2-3. SAM3N 48-pin version Block Diagramz



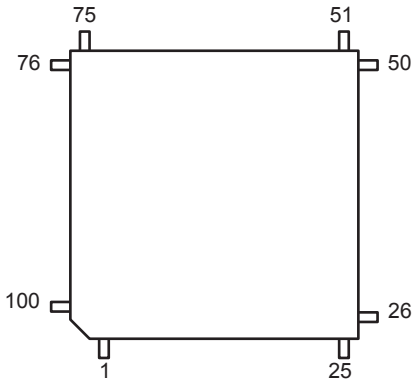
4. Package and Pinout

SAM3N4/2/1/0/00 series is pin-to-pin compatible with SAM3S products. Furthermore SAM3N4/2/1/0/00 devices have new functionalities referenced in italic inTable 4-1, Table 4-3 and Table 4-4.

4.1 SAM3N4/2/1/0/00C Package and Pinout

4.1.1 100-lead LQFP Package Outline

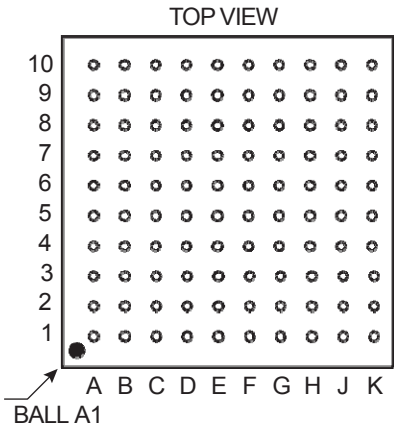
Figure 4-1. Orientation of the 100-lead LQFP Package



4.1.2 100-ball TFBGA Package Outline

The 100-Ball TFBGA package has a 0.8 mm ball pitch and respects Green Standards. Its dimensions are 9 x 9 x 1.1 mm.

Figure 4-2. Orientation of the 100-ball TFBGA Package



4.1.3 100-Lead LQFP Pinout

Table 4-1. 100-lead LQFP SAM3N4/2/1/0/00C Pinout

1	ADVREF	26	GND	51	TDI/PB4	76	TDO/TRACESWO/PB5
2	GND	27	VDDIO	52	PA6/PGMNOE	77	JTAGSEL
3	PB0/AD4	28	PA16/PGMD4	53	PA5/PGMRDY	78	PC18
4	PC29/AD13	29	PC7	54	PC28	79	TMS/SWDIO/PB6
5	PB1/AD5	30	PA15/PGMD3	55	PA4/PGMNCMD	80	PC19
6	PC30/AD14	31	PA14/PGMD2	56	VDDCORE	81	PA31
7	PB2/AD6	32	PC6	57	PA27	82	PC20
8	PC31/AD15	33	PA13/PGMD1	58	PC8	83	TCK/SWCLK/PB7
9	PB3/AD7	34	PA24	59	PA28	84	PC21
10	VDDIN	35	PC5	60	NRST	85	VDDCORE
11	VDDOUT	36	VDDCORE	61	TST	86	PC22
12	PA17/PGMD5/AD0	37	PC4	62	PC9	87	ERASE/PB12
13	PC26	38	PA25	63	PA29	88	PB10
14	PA18/PGMD6/AD1	39	PA26	64	PA30	89	PB11
15	PA21/AD8	40	PC3	65	PC10	90	PC23
16	VDDCORE	41	PA12/PGMD0	66	PA3	91	VDDIO
17	PC27	42	PA11/PGMM3	67	PA2/PGMEN2	92	PC24
18	PA19/PGMD7/AD2	43	PC2	68	PC11	93	PB13/DAC0
19	PC15/AD11	44	PA10/PGMM2	69	VDDIO	94	PC25
20	PA22/AD9	45	GND	70	GND	95	GND
21	PC13/AD10	46	PA9/PGMM1	71	PC14	96	PB8/XOUT
22	PA23	47	PC1	72	PA1/PGMEN1	97	PB9/*PGMCK/XIN*
23	PC12/AD12	48	PA8/XOUT32/ PGMM0	73	PC16	98	VDDIO
24	PA20/AD3	49	PA7/XIN32/ PGMNVALID	74	PA0/PGMEN0	99	PB14
25	PC0	50	VDDIO	75	PC17	100	VDDPLL

4.3 SAM3N4/2/1/0/00A Package and Pinout

Figure 4-5. Orientation of the 48-pad QFN Package

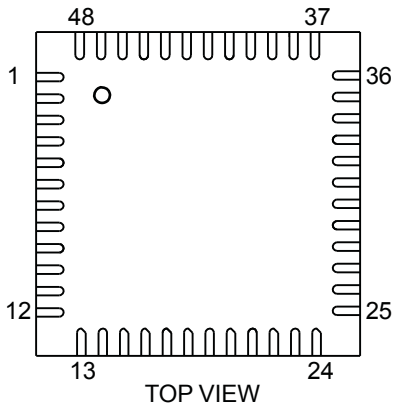
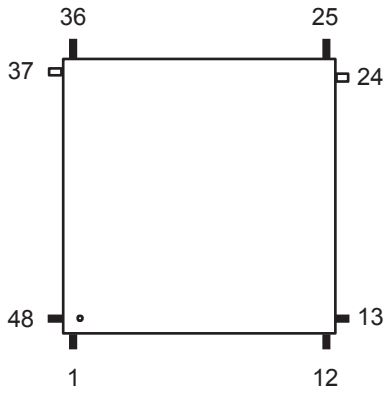


Figure 4-6. Orientation of the 48-lead LQFP Package



5.7 Fast Start-Up

The SAM3N allows the processor to restart in a few microseconds while the processor is in wait mode. A fast start up can occur upon detection of a low level on one of the 19 wake-up inputs (WKUP0 to 15 + SM + RTC + RTT).

The fast restart circuitry, as shown in Figure 5-5, is fully asynchronous and provides a fast start-up signal to the Power Management Controller. As soon as the fast start-up signal is asserted, the PMC automatically restarts the embedded 4 MHz fast RC oscillator, switches the master clock on this 4 MHz clock and reenables the processor clock.

Figure 5-5. Fast Start-Up Sources

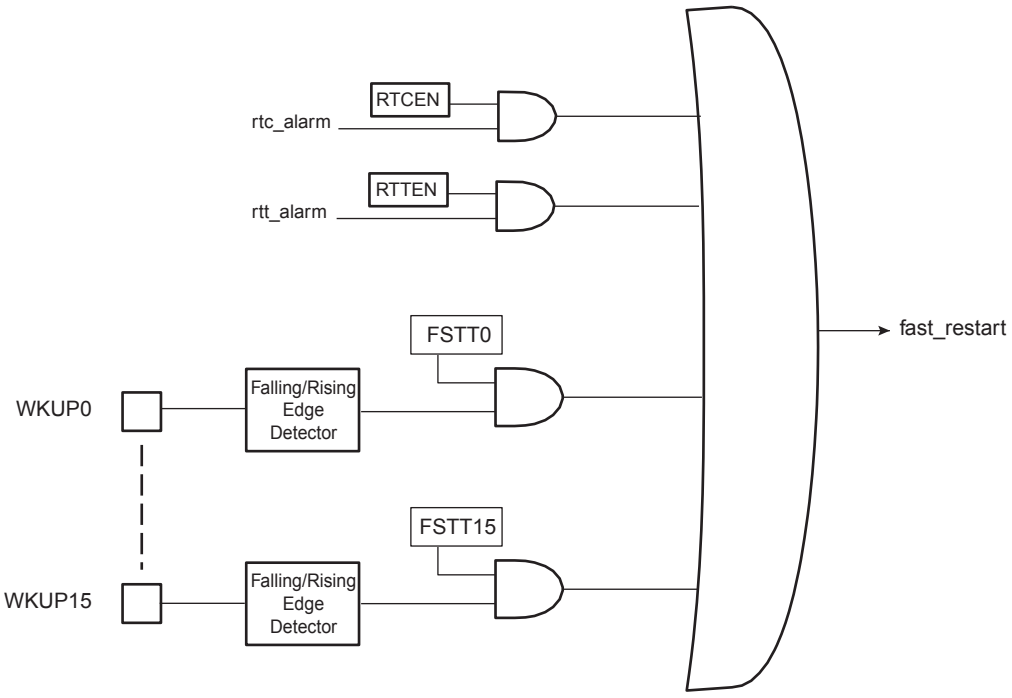


Table 6-1. System I/O Configuration Pin List.

SYSTEM_IO bit number	Default function after reset	Other function	Constraints for normal start	Configuration
12	ERASE	PB12	Low Level at startup(1)	In Matrix User Interface Registers (Refer to the System I/O Configuration Register in the Bus Matrix section of the product datasheet.)
7	TCK/SWCLK	PB7	-	
6	TMS/SWDIO	PB6	-	
5	TDO/TRACESWO	PB5	-	
4	TDI	PB4	-	
-	PA7	XIN32	-	See footnote (2) below
-	PA8	XOUT32	-	
-	PB9	XIN	-	See footnote (3) below
-	PB8	XOUT	-	

Notes:
1. If PB12 is used as PIO input in user applications, a low level must be ensured at startup to prevent Flash erase before the user application sets PB12 into PIO mode.
2. In the product Datasheet Refer to: Slow Clock Generator of the Supply Controller section.
3. In the product Datasheet Refer to: 3 to 20 MHZ Crystal Oscillator information in the PMC section.

6.2.1 Serial Wire JTAG Debug Port (SWJ-DP) Pins

The SWJ-DP pins are TCK/SWCLK, TMS/SWDIO, TDO/SWO, TDI and commonly provided on a standard 20-pin JTAG connector defined by ARM. For more details about voltage reference and reset state, refer to Table 3-1 on page 7.

At startup, SWJ-DP pins are configured in SWJ-DP mode to allow connection with debugging probe. Please refer to the Debug and Test Section of the product datasheet.

SWJ-DP pins can be used as standard I/Os to provide users more general input/output pins when the debug port is not needed in the end application. Mode selection between SWJ-DP mode (System IO mode) and general IO mode is performed through the AHB Matrix Special Function Registers (MATRIX_SFR). Configuration of the pad for pull-up, triggers, debouncing and glitch filters is possible regardless of the mode.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. It integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

By default, the JTAG Debug Port is active. If the debugger host wants to switch to the Serial Wire Debug Port, it must provide a dedicated JTAG sequence on TMS/SWDIO and TCK/SWCLK which disables the JTAG-DP and enables the SW-DP. When the Serial Wire Debug Port is active, TDO/TRACESWO can be used for trace.

The asynchronous TRACE output (TRACESWO) is multiplexed with TDO. So the asynchronous trace can only be used with SW-DP, not JTAG-DP. For more information about SW-DP and JTAG-DP switching, please refer to the Debug and Test Section.

7.5 Master to Slave Access

All the Masters can normally access all the Slaves. However, some paths do not make sense, for example allowing access from the Cortex-M3 S Bus to the Internal ROM. Thus, these paths are forbidden or simply not wired, and shown as "-" in Table 7-3.

Table 7-3. SAM3N Master to Slave Access

Masters		0	1	2
Slaves		Cortex-M3 I/D Bus	Cortex-M3 S Bus	PDC
0	Internal SRAM	-	X	X
1	Internal ROM	X	-	X
2	Internal Flash	X	-	-
3	Peripheral Bridge	-	X	X

7.6 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirement

The Peripheral DMA Controller handles transfer requests from the channel according to the following priorities (Low to High priorities):

Table 7-4. Peripheral DMA Controller

Instance name	Channel T/R	100 & 64 Pins	48 Pins
TWI0	Transmit	x	x
UART0	Transmit	x	x
USART0	Transmit	x	x
DAC	Transmit	x	N/A
SPI	Transmit	x	x
TWI0	Receive	x	x
UART0	Receive	x	x
USART0	Receive	x	x
ADC	Receive	x	x
SPI	Receive	x	x

7.7 Debug and Test Features

- Debug access to all memory and registers in the system, including Cortex-M3 register bank when the core is running, halted, or held in reset.
- Serial Wire Debug Port (SW-DP) and Serial Wire JTAG Debug Port (SWJ-DP) debug access
- Flash Patch and Breakpoint (FPB) unit for implementing breakpoints and code patches
- Data Watchpoint and Trace (DWT) unit for implementing watchpoints, data tracing, and system profiling
- Instrumentation Trace Macrocell (ITM) for support of printf style debugging
- IEEE1149.1 JTAG Boundary-can on All Digital Pins

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The SAM3N4 product embeds a total of 24-Kbytes high-speed SRAM.

The SAM3N2 product embeds a total of 16-Kbytes high-speed SRAM.

The SAM3N1 product embeds a total of 8-Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is from 0x2200 0000 and 0x23FF FFFF.

RAM size must be configurable by calibration fuses.

9.1.2 Internal ROM

The SAM3N product embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the SAM3N4 (256 Kbytes) is organized in one bank of 1024 pages of 256 bytes (Single plane).

The Flash of the SAM3N2 (128 Kbytes) is organized in one bank of 512 pages of 256 bytes (Single Plane).

The Flash of the SAM3N1 (64 Kbytes) is organized in one bank of 256 pages of 256 bytes (Single plane).

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32-bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

One of the commands returns the embedded Flash descriptor definition that informs the system about the Flash organization, thus making the software generic.

The reset circuitry is based on a zero-power power-on reset cell and a brownout detector cell. The zero-power power-on reset allows the Supply Controller to start properly, while the software-programmable brownout detector allows detection of either a battery discharge or main voltage loss.

The Slow Clock generator is based on a 32 kHz crystal oscillator and an embedded 32 kHz RC oscillator. The Slow Clock defaults to the RC oscillator, but the software can enable the crystal oscillator and select it as the Slow Clock source.

The Supply Controller starts up the device by sequentially enabling the internal power switches and the Voltage Regulator, then it generates the proper reset signals to the core power supply.

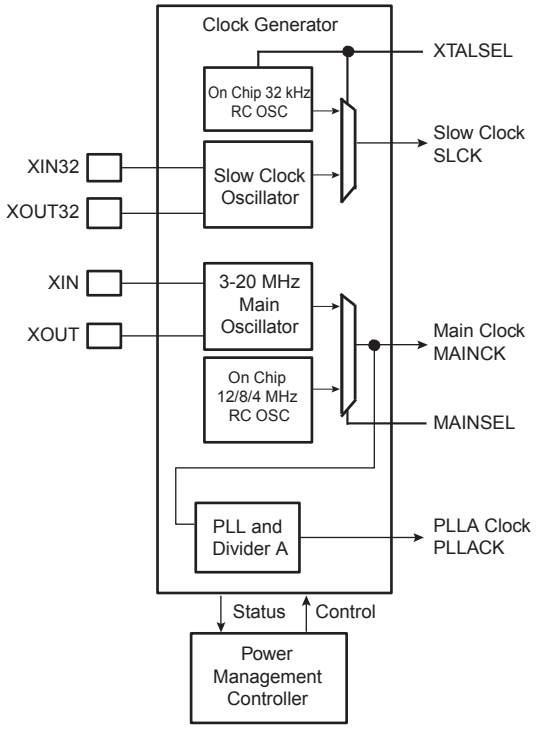
It also enables to set the system in different low power modes and to wake it up from a wide range of events.

10.5 Clock Generator

The Clock Generator is made up of:

- One Low Power 32768Hz Slow Clock Oscillator with bypass mode
- One Low-Power RC Oscillator
- One 3-20 MHz Crystal or Ceramic resonator Oscillator, which can be bypassed
- One Fast RC Oscillator factory programmed, 3 output frequencies can be selected: 4, 8 or 12 MHz. By default 4 MHz is selected.
- One 60 to 130 MHz programmable PLL, capable to provide the clock MCK to the processor and to the peripherals. The input frequency of PLL is from 3.5 to 20 MHz.

Figure 10-2. Clock Generator Block Diagram



10.6 Power Management Controller

The Power Management Controller provides all the clock signals to the system. It provides:

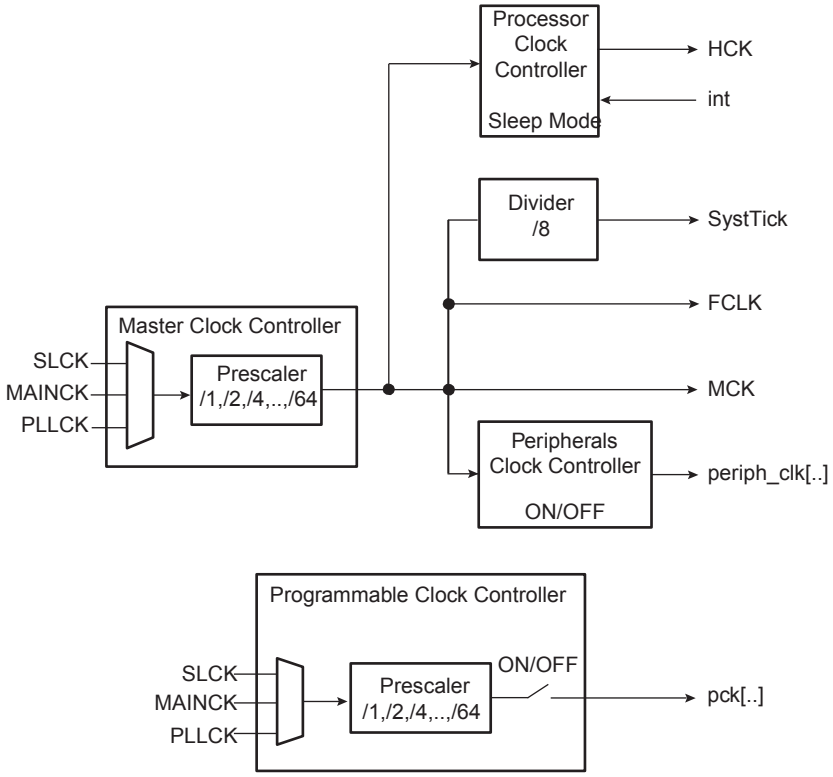
- the Processor Clock HCLK
- the Free running processor clock FCLK
- the Cortex SysTick external clock
- the Master Clock MCK, in particular to the Matrix and the memory interfaces
- independent peripheral clocks, typically at the frequency of MCK
- three programmable clock outputs: PCK0, PCK1 and PCK2

The Supply Controller selects between the 32 kHz RC oscillator or the crystal oscillator. The unused oscillator is disabled automatically so that power consumption is optimized.

By default, at startup the chip runs out of the Master Clock using the Fast RC Oscillator running at 4 MHz.

The user can trim by software the 8 and 12 MHz RC Oscillator frequency.

Figure 10-3. SAM3N4/2/1/0/00 Power Management Controller Block Diagram



The SysTick calibration value is fixed at 6000 which allows the generation of a time base of 1 ms with SysTick clock at 6 MHz (48 MHz/8)

10.7 Watchdog Timer

- 16-bit key-protected only-once-Programmable Counter
- Windowed, prevents the processor to be in a dead-lock on the watchdog access

10.8 SysTick Timer

- 24-bit down counter
- Self-reload capability
- Flexible System timer

10.9 Real-time Timer

- Real-time Timer, allowing backup of time with different accuracies
  - 32-bit Free-running back-up Counter
  - Integrates a 16-bit programmable prescaler running on slow clock
  - Alarm register capable to generate a wake-up of the system through the Shut Down Controller

10.10 Real Time Clock

- Low power consumption
- Full asynchronous design
- Two hundred year calendar
- Programmable Periodic Interrupt
- Alarm and update parallel load
- Control of alarm and update Time/Calendar Data In

10.11 General Purpose Backup Registers

- Eight 32-bit general-purpose backup registers

10.12 Nested Vectored Interrupt Controller

- Thirty Two maskable external interrupts
- Sixteen priority levels
- Processor state automatically saved on interrupt entry, and restored on
- Dynamic reprioritization of interrupts
- Priority grouping
  - selection of pre-empting interrupt levels and non pre-empting interrupt levels
- Support for tail-chaining and late arrival of interrupts
  - back-to-back interrupt processing without the overhead of state saving and restoration between interrupts.
- Processor state automatically saved on interrupt entry and restored on interrupt exit, with no instruction overhead

  - Two multi-purpose input/output signals
- Two global registers that act on all three TC Channels
- Quadrature decoder
  - Advanced line filtering
  - Position/revolution/speed
- 2-bit Gray Up/Down Counter for Stepper Motor

12.6 Pulse Width Modulation Controller (PWM)

- Four channels, one 16-bit counter per channel
- Common clock generator, providing thirteen different clocks
  - One Modulo n counter providing eleven clocks
  - Two independent linear dividers working on modulo n counter outputs
- Independent channel programming
  - Independent enable/disable commands
  - Independent clock selection
  - Independent period and duty cycle, with double buffering
  - Programmable selection of the output waveform polarity

12.7 10-bit Analog-to-Digital Converter

- Up to 16-channel ADC
- 10-bit 384 Ksamples/sec. or 8-bit 583 Ksamples/sec. Successive Approximation Register ADC
- ±2 LSB Integral Non Linearity, ±1 LSB Differential Non Linearity
- Integrated 8-to-1 multiplexer, offering eight independent 3.3V analog inputs
- External voltage reference for better accuracy on low voltage inputs
- Individual enable and disable of each channel
- Multiple trigger source
  - Hardware or software trigger
  - External trigger pin
  - Timer Counter 0 to 2 outputs TIOA0 to TIOA2 trigger
- Sleep Mode and conversion sequencer
  - Automatic wakeup on trigger and back to sleep mode after conversions of all enabled channels

12.8 Digital-to-Analog Converter (DAC)

- 1 channel 10-bit DAC
- Up to 500 ksamples/s conversion rate
- Flexible conversion range
- Multiple trigger sources
- One PDC channel

Table 13-1. 48-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	9.00 BSC			0.354 BSC		
D1	7.00 BSC			0.276 BSC		
E	9.00 BSC			0.354 BSC		
E1	7.00 BSC			0.276 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	5.50			0.217		
E2	5.50			0.217		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Table 13-3. 48-pad QFN Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	090	–	–	0.035
A1	–	–	0.050	–	–	0.002
A2	–	0.65	0.70	–	0.026	0.028
A3	0.20 REF			0.008 REF		
b	0.18	0.20	0.23	0.007	0.008	0.009
D	7.00 bsc			0.276 bsc		
D2	5.45	5.60	5.75	0.215	0.220	0.226
E	7.00 bsc			0.276 bsc		
E2	5.45	5.60	5.75	0.215	0.220	0.226
L	0.35	0.40	0.45	0.014	0.016	0.018
e	0.50 bsc			0.020 bsc		
R	0.09	–	–	0.004	–	–
Tolerances of Form and Position						
aaa	0.10			0.004		
bbb	0.10			0.004		
ccc	0.05			0.002		

14. Ordering Information

Table 14-1.

Ordering Code	MRL	Flash (Kbytes)	Package	Package Type	Temperature Operating Range
ATSAM3N4CA-AU	A	256	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N4CA-CU	A	256	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N4BA-AU	A	256	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N4BA-MU	A	256	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N4AA-AU	A	256	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N4AA-MU	A	256	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N2CA-AU	A	128	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N2CA-CU	A	128	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N2BA-AU	A	128	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N2BA-MU	A	128	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N2AA-AU	A	128	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N2AA-MU	A	128	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N1CA-AU	A	64	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N1CB-AU	B	64	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N1CA-CU	A	64	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N1CB-CU	B	64	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N1BA-AU	A	64	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N1BB-AU	B	64	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N1BA-MU	A	64	QFN 64	Green	Industrial -40°C to 85°C
ATSAM3N1BB-MU	B	64	QFN 64	Green	Industrial -40°C to 85°C

Table 14-1.

Ordering Code	MRL	Flash (Kbytes)	Package	Package Type	Temperature Operating Range
ATSAM3N1AA-AU	A	64	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N1AB-AU	B	64	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N1AA-MU	A	64	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N1AB-MU	B	64	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N0CA-AU	A	32	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N0CA-CU	A	32	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N0BA-AU	A	32	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N0BA-MU	A	32	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N0AA-AU	A	32	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N0AA-MU	A	32	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N00BA-AU	A	16	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N00BA-MU	A	16	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N00AA-AU	A	16	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N00AA-MU	A	16	QFN48	Green	Industrial -40°C to 85°C

Revision History

Doc. Rev. 11011BS	Comments	Change Request Ref.
	Overview:	
	All mentions of 100-ball LFBGA changed into 100-ball TFBGA	8044
	Section 8. “Product Mapping”, Heading was ‘Memories’. Changed to ‘Product Mapping’	7685
	Section 4.1.4 “100-ball TFBGA Pinout”, whole pinout table updated	7201
	Updated package dimensions in ‘Features’	7965

Doc. Rev	Comments	Change Request Ref.
11011AS	First issue	